



NOEL Technologies

NOEL PROCESS FLOW: 128

Low Particle Clean

Revision: 0 Date: November 14, 2007

Process Steps	Process Flow	Process Details
Single Wafer	LPC Clean	80:2:1 DI Water 80 Parts,
1		Hydrogen Peroxide 2 Parts, Ammonia Hydroxide 1 Part
2	Spin Dry	Inspect Wafer

Note: Above process for Non-Patterned Wafers.

Patterned wafers require a technical review of the feature size, films prior to accepting material.

Evergreen, single wafer scrubber. Substrates up to 300mm, as well as solar and non-standard substrates.